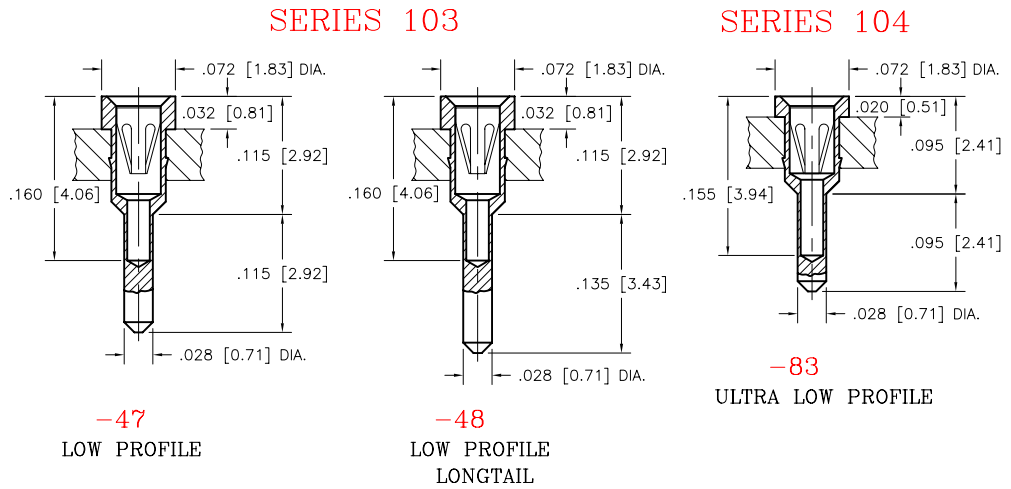
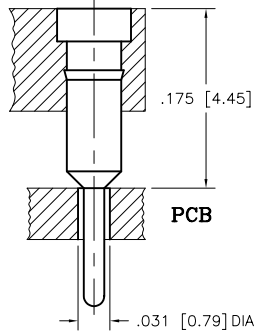
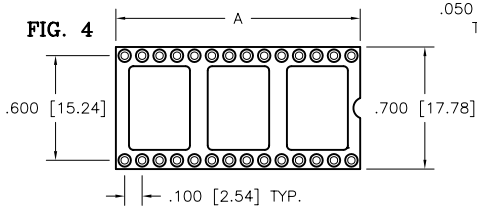
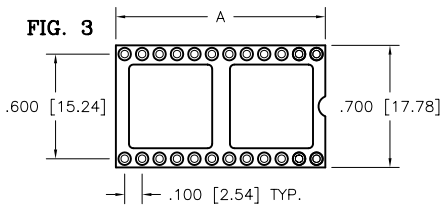
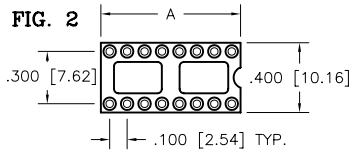
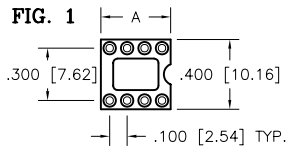


SERIES 103 LOW PROFILE DIP SOCKET (OPEN FRAME)
SERIES 104 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME)
SERIES 105 ULTRA LOW PROFILE DIP SOCKET (OPEN FRAME WITHOUT CROSSBARS)

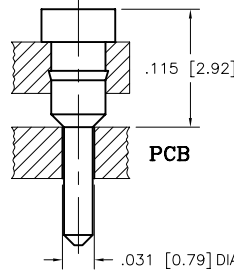
WAFER CHART			
	PIN	DIM "A"	
FIG. 1	6	.300 [7.62]	306
	8	.400 [10.16]	308
FIG. 2	14	.700 [17.78]	314
	16	.800 [20.32]	316
	18	.900 [22.86]	318
	20	1.000 [25.40]	320
	22	1.100 [27.94]	322
	24	1.200 [30.48]	324
FIG. 3	24	1.200 [30.48]	624
	28	1.400 [35.56]	628
FIG. 4	30	1.500 [38.10]	630
	32	1.600 [40.64]	632
	36	1.800 [45.72]	636
	40	2.000 [50.80]	640



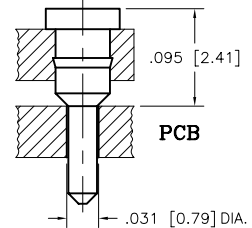
STANDARD HEIGHT ABOVE PCB WITH -01 TERMINAL



34% REDUCED HEIGHT WITH -47 TERMINAL



46% REDUCED HEIGHT WITH -83 TERMINAL



CONTACT TYPE

S: STANDARD DIP	INSERTION FORCE	9.0 oz. AVG.
	WITHDRAWAL FORCE	2.0 oz. MIN.
M: STANDARD PGA	INSERTION FORCE	1.6 oz. MAX.
	WITHDRAWAL FORCE	0.5 oz. MIN.
L: INTERSTITIAL PGA	INSERTION FORCE	1.0 oz. MAX.
	WITHDRAWAL FORCE	0.3 oz. MIN.
H: HIGH FORCE	INSERTION FORCE	18.3 oz. MAX.
	WITHDRAWAL FORCE	4.2 oz. MIN.

TECHNICAL SPECIFICATIONS

MATERIAL
INSULATOR GLASS FILLED POLYESTER
 UL 94V-0 LISTED
TERMINAL BRASS PER ASTM-B16
CONTACT BeCu PER ASTM-B194
OPERATING TEMP. -65°C TO +125°C

CONTACT FORCES
INSERTION STANDARD 9 oz. AVG.
WITHDRAWAL STANDARD 2 oz. MIN.

ORDERING INFORMATION

